

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1585	257/779	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/04 23:31
L2	1131	257/781	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/04 23:37
L3	1039	257/782	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/04 23:37
S1	0	"20030030153"	USPAT	OR	OFF	2005/08/04 23:19
S2	1	"20030030153"	US-PGPUB; USPAT	OR	OFF	2004/07/11 19:32
S3	2	"6018462"	US-PGPUB; USPAT	OR	OFF	2004/07/11 19:34
S4	1	"5519580".PN.	USPAT	OR	OFF	2004/07/11 19:33
S5	1	"6028366".PN.	USPAT	OR	OFF	2004/07/11 19:34
S6	1	"6225573".PN.	USPAT	OR	OFF	2004/07/11 19:34
S7	1	"6246587".PN.	USPAT	OR	OFF	2004/07/11 19:34
S8	1	"6329605".PN.	USPAT	OR	OFF	2004/07/11 19:34
S9	1039147	pad with multi\$4 with (under or lower) layer	US-PGPUB; USPAT	OR	OFF	2004/07/11 19:35
S10	1038997	pad with multi\$4 near (under or lower) layer	US-PGPUB; USPAT	OR	OFF	2004/07/11 19:36
S11	0	pad with multi\$4 near (under or lower) near layers	USPAT	OR	ON	2004/07/11 19:36
S12	33	pad with multi\$4 with (under or lower) near layers	USPAT	OR	ON	2004/07/11 19:49
S13	1598	pad with multi\$4 near layers	USPAT	OR	ON	2004/07/11 20:10
S14	47	(pad with multi\$4 near layers) and 257/781	USPAT	OR	ON	2004/07/11 20:10
S15	9	"5378927"	USPAT	OR	ON	2004/07/11 20:00
S16	203	pad with multi\$4 near layers with (solder or ball or bump)	USPAT	OR	ON	2004/07/11 20:00
S17	145	pad with multi\$4 near layers with (solder )	USPAT	OR	ON	2004/07/11 20:01

S18	26	(pad with multi\$4 near layers) and 257/782	USPAT	OR	ON	2004/07/11 20:12
S19	787	257/782	USPAT	OR	ON	2004/07/11 20:51
S20	1296	257/779	USPAT	OR	ON	2004/07/11 20:51
S21	1108	257/779 and solder	USPAT	OR	ON	2004/07/11 20:52
S22	71	257/779 and solder and pad with (lower or bottom or multi\$4) near (layer or film)	USPAT	OR	ON	2004/07/11 20:57
S23	126	(257/779 or 257/780 or 257/781) and solder and pad with (lower or bottom or multi\$4) near (layer or film)	USPAT	OR	ON	2004/07/11 21:04
S24	1	"4680610".PN.	USPAT	OR	OFF	2004/07/11 20:59
S25	1	"5422516".PN.	USPAT	OR	OFF	2004/07/11 21:00
S26	1	"5442241".PN.	USPAT	OR	OFF	2004/07/11 21:00
S27	1	"5569960".PN.	USPAT	OR	OFF	2004/07/11 21:00
S28	1	"5587341".PN.	USPAT	OR	OFF	2004/07/11 21:00
S29	1	"5731636".PN.	USPAT	OR	OFF	2004/07/11 21:01
S30	1	"5744859".PN.	USPAT	OR	OFF	2004/07/11 21:01
S31	2029	(semiconductor or die or chip or IC) and pad with (lower or bottom or multi\$4) near (layers or films)	USPAT	OR	ON	2004/07/11 21:05
S32	1123	(semiconductor or die or chip or IC) and pad with multi\$4 near (layers or films)	USPAT	OR	ON	2004/07/11 22:05
S33	711	(semiconductor or die or chip or IC) and pad with two near (layers or films)	USPAT	OR	ON	2004/07/11 22:05
S34	3	(semiconductor or die or chip or IC) and pad with two near (lower or bottom) near (layers or films)	USPAT	OR	ON	2004/07/11 22:06
S35	0	(semiconductor or die or chip or IC) and pad with three near (lower or bottom) near (layers or films)	USPAT	OR	ON	2004/07/11 22:06
S36	4	(semiconductor or die or chip or IC) and pad with multi near (lower or bottom) near (layers or films)	USPAT	OR	ON	2004/07/11 22:07
S37	834	(semiconductor or die or chip or IC) and pad with barrier near (layers or films)	USPAT	OR	ON	2004/07/11 22:08
S38	1	"6822329"	USPAT	OR	OFF	2005/02/01 16:21
S39	1	"5736791".PN.	USPAT; USOCR	OR	OFF	2005/02/01 16:17
S40	1	"6100589".PN.	USPAT; USOCR	OR	OFF	2005/02/01 16:18

S41	1	"6198170".PN.	USPAT; USOCR	OR	OFF	2005/02/01 16:18
S42	1	"6297563".PN.	USPAT; USOCR	OR	OFF	2005/02/01 16:19
S43	1	"6313540".PN.	USPAT; USOCR	OR	OFF	2005/02/01 16:19
S44	1	"6448641".PN.	USPAT; USOCR	OR	OFF	2005/02/01 16:20
S45	1	"6313540".PN.	USPAT; USOCR	OR	OFF	2005/02/01 16:20
S46	1	"6313540".PN.	USPAT; USOCR	OR	OFF	2005/02/01 16:20
S47	24518	(semiconductor or die or chip or IC) and pad with connect\$3	USPAT	OR	OFF	2005/02/01 16:22
S48	1910	257/780	USPAT	OR	OFF	2005/02/03 18:36
S49	1005	257/781	USPAT	OR	OFF	2005/02/01 20:23
S50	2216	257/786	USPAT	OR	OFF	2005/02/02 23:22
S51	746648	"48" not "49"	USPAT	OR	OFF	2005/02/03 18:36
S52	1709	"s48" not "s49"	USPAT	OR	OFF	2005/02/03 18:40
S53	1170	(semiconductor or chip or die) and pad with multi\$4 near layers	USPAT	OR	ON	2005/02/03 19:27
S54	0	"6495917".pn. and bond near structure	USPAT	OR	ON	2005/02/03 19:27
S55	1	"6495917".pn. and pad near structure	USPAT	OR	ON	2005/02/03 19:28
S56	1825	257/779	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/08 14:58
S57	1136	257/781	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/08 16:21
S58	2	"6495917".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/08 15:11

S59	1187	257/782	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/08 16:38
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